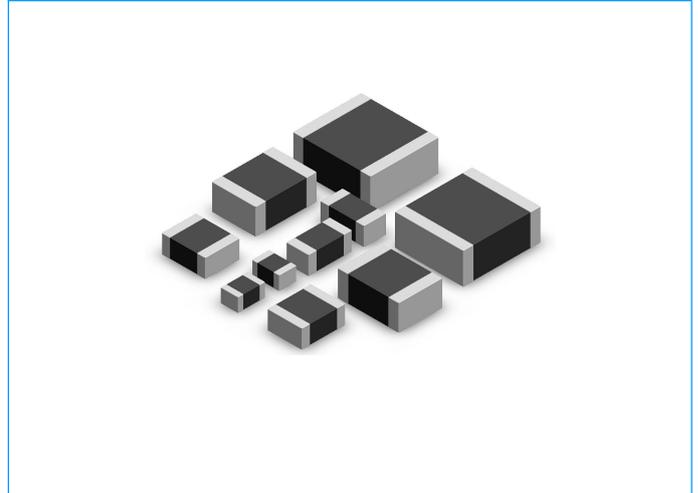


Surface Mount Multilayer Varistor

SV0806H271G0F

Description

The SV0806H271G0F is based on Multilayer fabrication technology. These components are designed to suppress a variety of transient events, including those specified in IEC 61000-4-2 or other standards used for Electromagnetic Compliance (EMC). The SV0806H271G0F is typically applied to protect integrated circuits and other components at the circuit board level. It can operate over a wider temperature range than zener diodes.



Features

- ◆ Rectangle, sizes serialization for hybrid integrated circuit or printed circuit surface mount components
- ◆ There are many side electrode lead-out material, particularly suitable for surface mount technology for solderability and resistance to soldering heat of the stringent requirements
- ◆ Fast response (<1ns)
- ◆ Low leakage current, low clamping voltage
- ◆ Suitable for reflow, wave soldering and hot air hand soldering

Applications

- ◆ Application for Mother Board, Notebook, Cellular Phone, PDA, handheld device, DSC, DV, Scanner, and Set- Top Box...etc.
- ◆ Suitable for Push-Button, Power Line and Low Frequency single line over-voltage protect.

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Electrical Characteristics (25±5°C)

Symbol	Minimum	Typical	Maximum	Units
V_{RMS}	—	—	175	V
V_{DC}	—	—	225	V
V_V	243	—	297	V
V_C	—	—	450	V
I_{max}	—	—	150	A

V_{RMS} - Maximum AC operating voltage the varistor can maintain and not exceed 10 μ A leakage current.

V_{DC} - Maximum DC operating voltage the varistor can maintain and not exceed 10 μ A leakage current.

V_V - Voltage across the device measure at 1mA DC current.

Equivalent to V_{BR} "breakdown voltage".

V_C - Maximum peak current across the varistor with 8/20 μ s waveform and 1A pulse current.

I_{max} - Maximum peak current which may be applied with 8/20 μ s waveform without device failure.

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Shape & Dimensions and Parts & Components

Shape & Dimensions: See Fig.1 and Table 1.

Parts & Components: See Fig.2 and Table 2.

Fig.1

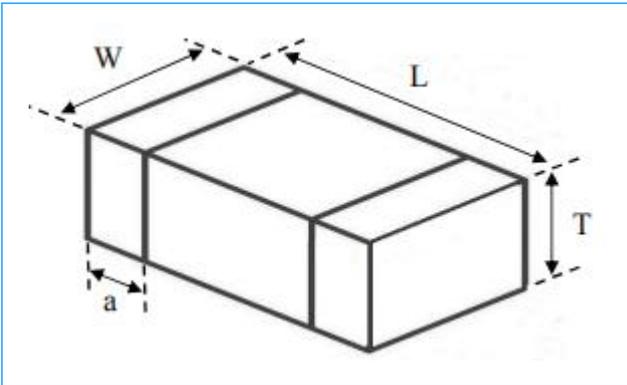


Table 1

Type	L (mm)	W (mm)	T (mm)	a (mm)
0806	2.3+0.2/-0.2	1.8+0.2/-0.2	2.0 Max.	0.50±0.30

Fig.2

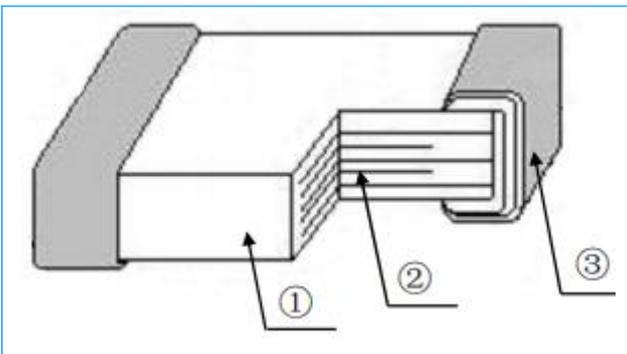


Table 2

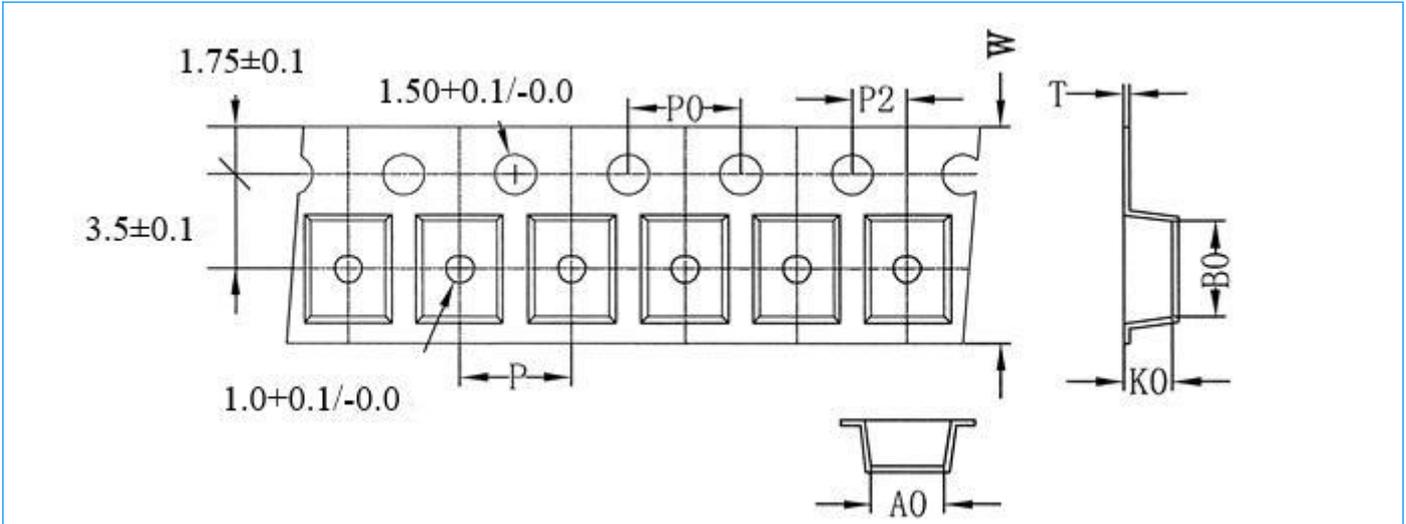
Part	①	②	③
Component	ZnO Semiconductor Ceramics for Chip Varistor	Internal Electrode (Ag or Ag-Pd)	Terminal Electrode (Ag/Ni/Sn three layers)

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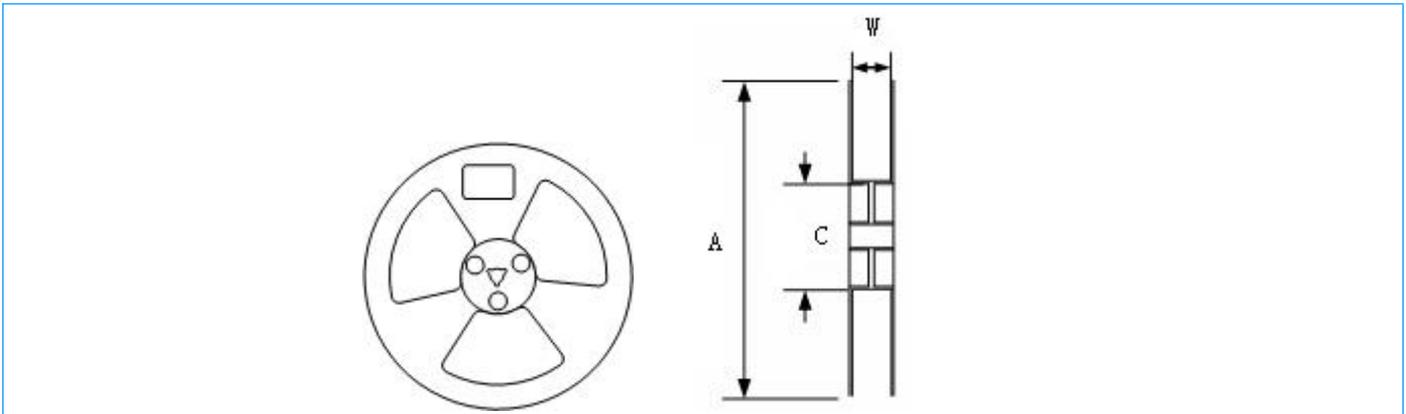
Taping

Carrier Tape Dimensions (Unit: mm)



Type	A0 (±0.2)	B0 (±0.2)	K0 Max.	T Max.	W (±0.3)	P0 (±0.2)	P (±0.2)	P2 (±0.2)
0806	2.1	2.5	2.5	0.3	8.0	4.0	4.0	2.0

Taping Reel Dimensions (Unit: mm)



Type	Spec.	Dimensions		
		A	W	C
0806	7"	178±2	8.4+2.0/-0.0	58±2

Packaging Quantity

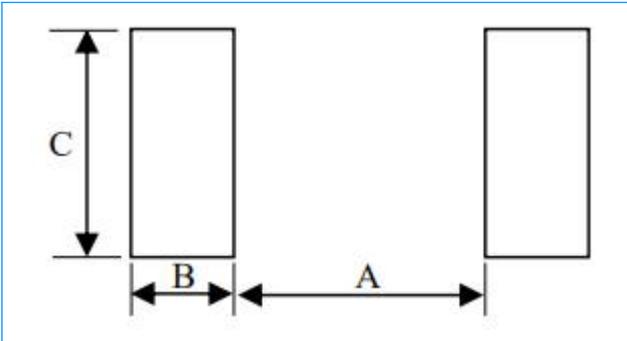
Type	Tape	Quantity (pcs/reel)
0806	Embossed Tape	2000

Surface Mount Multilayer Varistor

SV0806H271G0F

Soldering Recommendation

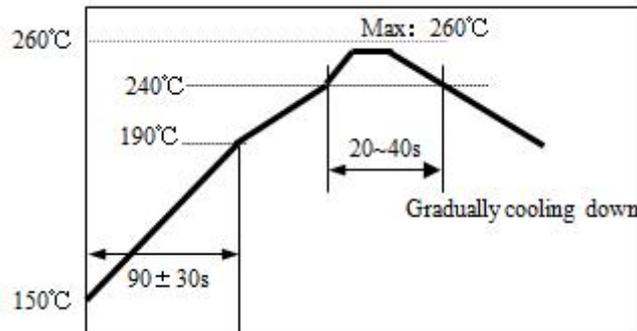
Recommended Land Pattern



Type	A (mm)	B (mm)	C (mm)
0806	1.4~1.8	0.8~1.2	1.8~2.2

Recommended Soldering Profile

- ◆ Pb Free Solder Paste: Sn/Ag/Cu (96.5/3.0/0.5).
- ◆ Max time at max temp: 10sec.
- ◆ Allowed Reflow time: 2x Max.



Notes & Warnings

- ◆ Storage temperature in original packaging: -10~+40°C.
- ◆ Relative Humidity: ≤70%RH.
- ◆ Keep away from corrosive atmosphere and sunlight.
- ◆ Period of Storage: 12 Months.